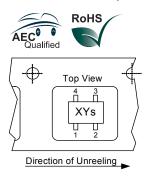


NPN Silicon Germanium RF Transistor*

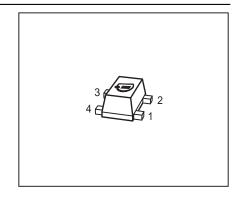
- For medium power amplifiers and driver stages
- High OIP3 and P-1dB
- Ideal for low phase noise oscilators
- Maxim. available Gain G_{ma} = 21.5 dB at 1.8 GHz
 Noise figure F = 0.8 dB at 1.8 GHz
- 70 GHz f_T- Silicon Germanium technology
- Pb-free (RoHS compliant) package 1)
- Qualified according AEC Q101
- * Short term description



ESD (Electrostatic discharge) sensitive device, observe handling precaution!

Туре	Marking	Pin Configuration					Package	
BFP650F	R5s	1=B	2=E	3=C	4=E	-	-	TSFP-4

¹Pb-containing package may be available upon special request





Maximum Ratings	M	laxim	um	Ratiı	ngs
-----------------	---	-------	----	-------	-----

Symbol	Value	Unit	
V_{CEO}		V	
	4		
	3.7		
V _{CES}	13		
V_{CBO}	13		
V_{EBO}	1.2		
I _C	150	mA	
I _B	10		
P _{tot}	500	mW	
T _i	150	°C	
T_{A}	-65 150		
T _{stq}	-65 150		
	V _{CES} V _{CBO} V _{CBO} V _{EBO} I _C I _B P _{tot} T _i T _A	V _{CEO} 4 3.7 V _{CES} 13 V _{CBO} 13 V _{CBO} 1.2 I _C 150 I _B 10 P _{tot} 500 T _i 150 T _A -65 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ²⁾	R _{thJS}	≤ 130	K/W

Electrical Characteristics at T_A = 25°C, unless otherwise specified

Parameter	Symbol	Values			Unit		
		min.	typ.	max.			
DC Characteristics							
Collector-emitter breakdown voltage	V _{(BR)CEO}	4	4.5	-	V		
$I_{\rm C}$ = 3 mA, $I_{\rm B}$ = 0							
Collector-emitter cutoff current	I _{CES}	-	-	100	μA		
$V_{CE} = 13 \text{ V}, V_{BE} = 0$							
Collector-base cutoff current	I _{CBO}	-	-	100	nA		
$V_{CB} = 5 \text{ V}, I_{E} = 0$							
Emitter-base cutoff current	I _{EBO}	-	-	10	μA		
$V_{\rm EB} = 0.5 \rm V, I_{\rm C} = 0$							
DC current gain	h _{FE}	110	180	270	-		
$I_{\rm C}$ = 80 mA, $V_{\rm CE}$ = 3 V, pulse measured							

 $^{^{1}}T_{\mbox{\scriptsize S}}$ is measured on the collector lead at the soldering point to the pcb

 $^{^2\}mbox{For calculation of}\,\mbox{\it R}_{\mbox{\scriptsize thJA}}$ please refer to Application Note Thermal Resistance



Electrical Characteristics at $T_A = 25$ °C, unless otherwise specified Unit **Parameter Symbol Values** min. typ. max. AC Characteristics (verified by random sampling) 42 GHz Transition frequency f_{T} $I_{\rm C}$ = 80 mA, $V_{\rm CE}$ = 3 V, f = 1 GHz 0.26 pF Collector-base capacitance C_{cb} $V_{CR} = 3 \text{ V}, f = 1 \text{ MHz}, V_{BE} = 0$, emitter grounded Collector emitter capacitance 0.45 C_{ce} $V_{CF} = 3 \text{ V}, f = 1 \text{ MHz}, V_{BF} = 0$, base grounded C_{eb} 1.3 Emitter-base capacitance $V_{EB} = 0.5 \text{ V}, f = 1 \text{ MHz}, V_{CB} = 0$ collector grounded F dB Noise figure $I_{\rm C}$ = 10 mA, $V_{\rm CF}$ = 3 V, f = 1.8 GHz, $Z_{\rm S}$ = $Z_{\rm Sopt}$ 8.0 I_{C} = 10 mA, V_{CE} = 3 V, f = 6 GHz, Z_{S} = Z_{Sopt} 1.9 Power gain, maximum available¹⁾ G_{ma} $I_{\rm C}$ = 80 mA, $V_{\rm CF}$ = 3 V, $Z_{\rm S}$ = $Z_{\rm Sopt}$, $Z_{\rm L}$ = $Z_{\rm Lopt}$, f = 1.8 GHz21.5 f = 6 GHz11 $|S_{21e}|^2$ Transducer gain dB $I_{\rm C}$ = 80 mA, $V_{\rm CF}$ = 3 V, $Z_{\rm S}$ = $Z_{\rm I}$ = 50 Ω , f = 1.8 GHz15 17.5 f = 6 GHz7.5 Third order intercept point at output²⁾ IP_3 dBm 31 $V_{CF} = 3 \text{ V}, I_{C} = 80 \text{ mA}, f = 1.8 \text{ GHz},$ $Z_{\rm S} = Z_{\rm I} = 50 \ \Omega$ 1dB Compression point at output P_{-1dB} 17.5 $I_{\rm C}$ = 80 mA, $V_{\rm CF}$ = 3 V, $Z_{\rm S}$ = $Z_{\rm L}$ = 50 Ω , f = 1.8 GHz

 $^{{}^{1}}G_{\text{ma}} = |S_{21e} / S_{12e}| (k - (k^{2} - 1)^{1/2})$

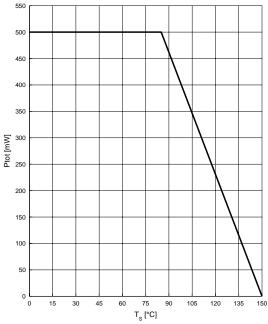
²IP3 value depends on termination of all intermodulation frequency components.

Termination used for this measurement is 50Ω from 0.1 MHz to 6 GHz

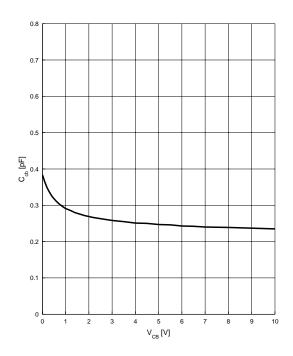


Total power dissipation $P_{tot} = f(T_S)$

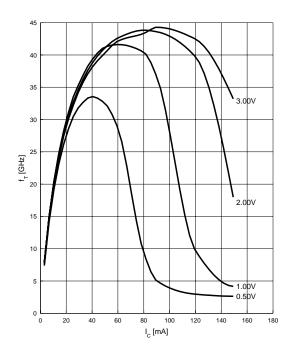
Collector-base capacitance $C_{cb} = f (V_{CB})$ f = 1 MHz

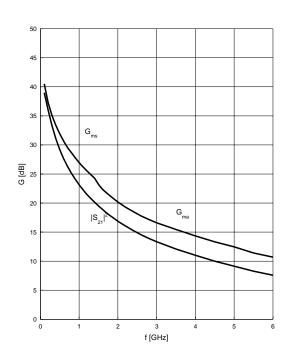


Transition frequency $f_T = f(I_C)$ V_{CE} = parameter in V, f = 1 GHz



Power gain G_{ma} , $G_{ms} = f(f)$ $V_{CE} = 3 \text{ V}$, $I_{C} = 80 \text{ mA}$



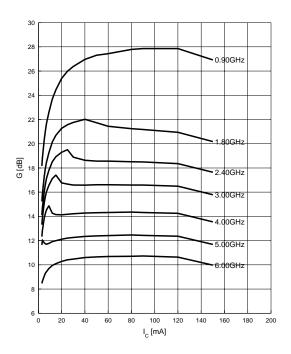




Power gain G_{ma} , $G_{ms} = f(I_C)$

 V_{CE} = 3 V

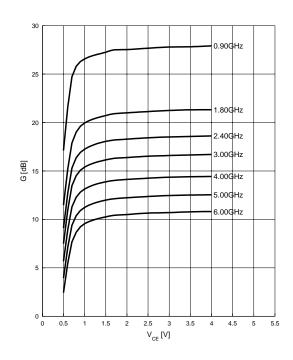
f = parameter in GHz



Power gain G_{ma} , $G_{ms} = f(V_{CE})$

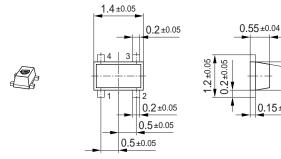
 $I_{\rm C}$ = 80 mA

f = parameter in GHz

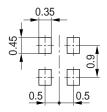




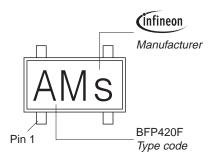
Package Outline



Foot Print

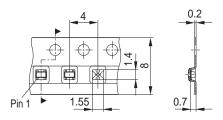


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel





Edition 2006-02-01 Published by Infineon Technologies AG 81726 München, Germany © Infineon Technologies AG 2007. All Rights Reserved.

Attention please!

The information given in this dokument shall in no event be regarded as a guarantee of conditions or characteristics ("Beschaffenheitsgarantie"). With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation warranties of non-infringement of intellectual property rights of any third party.

Information

For further information on technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies Office (www.infineon.com).

Warnings

Due to technical requirements components may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies Office.

Infineon Technologies Components may only be used in life-support devices or systems with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system, or to affect the safety or effectiveness of that device or system.

Life support devices or systems are intended to be implanted in the human body, or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.